

ABSTRACT

An epoxy resin composition for semiconductor encapsulation which does not contain conductive foreign metallic particles having such a size that they cannot be detected and eliminated by the conventional method for eliminating conductive foreign metallic particles. The epoxy resin composition for semiconductor encapsulation comprises the following components (A) to (D). Conductive foreign metallic particles having a size of 20 μm or more are substantially not contained in the aforementioned epoxy resin composition.

(A) An epoxy resin.

(B) A phenol resin.

(C) A hardening accelerator.

(D) An inorganic filler.